

**描述 / Descriptions**

1A 表面贴装玻璃钝化整流桥，薄型 ABS/LBF 封装。  
1A Surface Mount Glass Passivated Bridge Rectifier, ABS/LBF thin package.

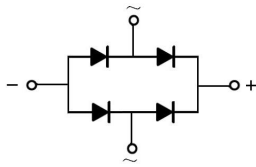
**特征 / Features**

玻璃钝化芯片，反向电压：100V~1000V，正向电流：1.0A，浪涌电流大，适用表面贴装。无卤产品。  
Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V, Forward Current: 1.0A, High Surge Current Capability, Designed for Surface Mount Application. Halogen free product.

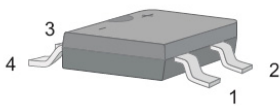
**用途 / Applications**

一般用途。  
General purpose.

**内部等效电路 / Equivalent Circuit**

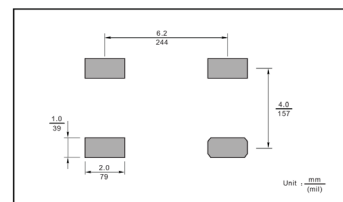


**引脚排列 / Pinning**



PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )

The recommended mounting pad size



**印章代码 / Marking**

见印章说明。See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		TB1S-10	TB2S-10	TB4S-10	TB6S-10	TB8S-10	TB10S-10	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 50°C	$I_o$	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	35						A
Typical Junction Capacitance <sup>(Note1)</sup>	$C_j$	13						pF
Typical Thermal Resistance <sup>(Note2)</sup>	$R_{\theta JA}$	80						°C/W
	$R_{\theta JL}$	25						°C/W
Junction Temperature, Storage Temperature Range	$T_j, T_{stg}$	-55~150						°C

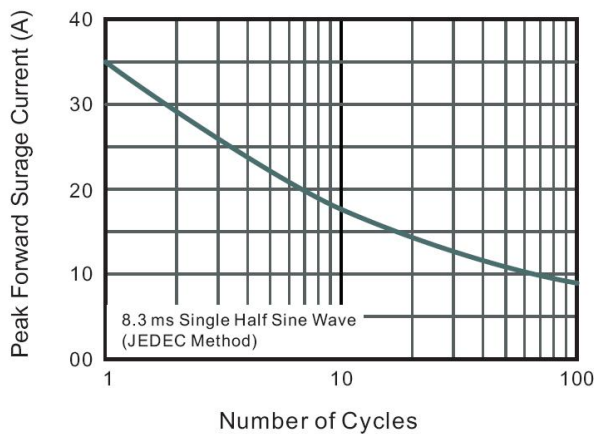
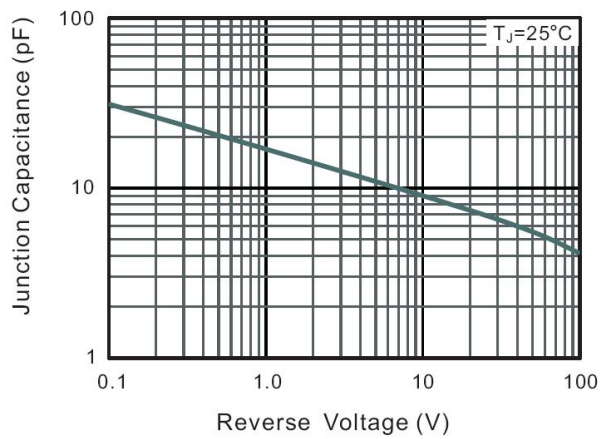
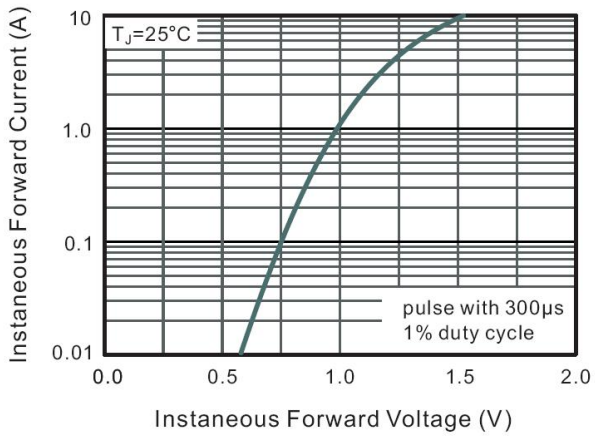
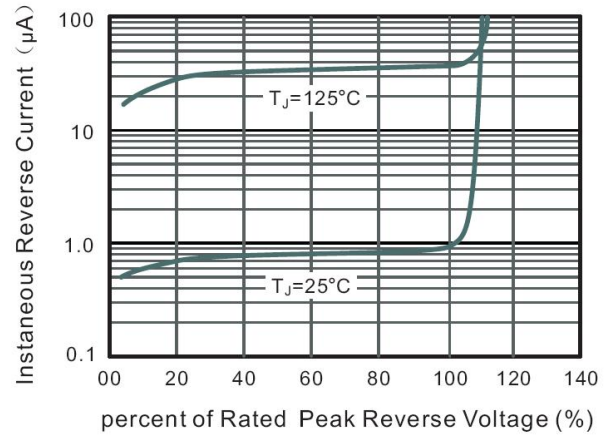
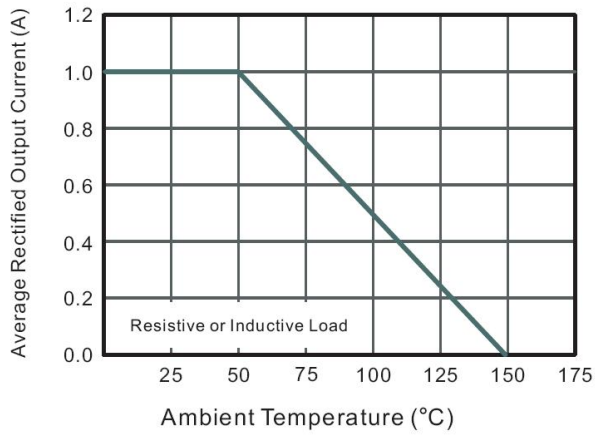
Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×( 5×5mm<sup>2</sup> ) copper pad..

**电性能参数 / Electrical Characteristics(Ta=25°C)**

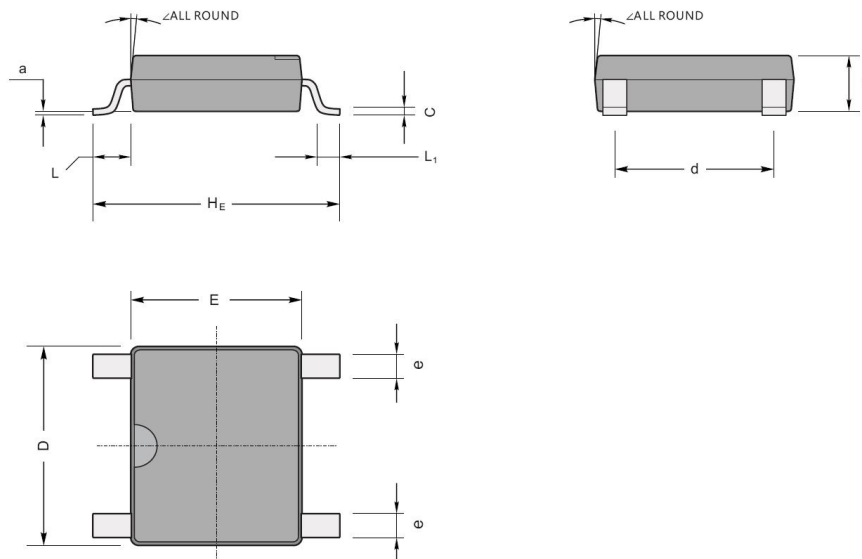
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	$V_F$	$I_F=1.0A$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	$I_R$	$T_a=25^\circ C$	5.0	μA
		$T_a=100^\circ C$	50	μA
		$T_a=125^\circ C$	100	μA

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

ABS/LBF



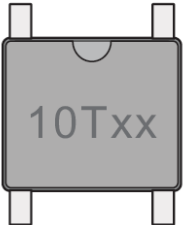
ABS/LBF mechanical data

UNIT		A	C	D	E	HE	d	e	L	L <sub>1</sub>	a	∠
mm	max	1.5	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.3	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	59	8.7	205	177	252	165	28	37	24	4	
	min	51	5.9	193	166	236	150	20				

印章说明 / Marking Instructions

### Marking

Type number	Marking code
TB1S-10	10T1
TB2S-10	10T2
TB4S-10	10T4
TB6S-10	10T6
TB8S-10	10T8
TB10S-10	10T10

The diagram shows a rectangular component with four pins. The marking code '10Txx' is printed on the top surface of the component.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度  $25 \sim 150^\circ\text{C}$ ，时间  $60 \sim 90 \text{ sec}$ ；
- 2、峰值温度  $245 \pm 5^\circ\text{C}$ ，时间持续为  $5 \pm 0.5 \text{ sec}$ ；
- 3、焊接制程冷却速度为  $2 \sim 10^\circ\text{C}/\text{sec}$ 。

Note:

- 1.Preheating: $25 \sim 150^\circ\text{C}$ , Time: $60 \sim 90 \text{ sec}$ .
- 2.Peak Temp.: $245 \pm 5^\circ\text{C}$ , Duration: $5 \pm 0.5 \text{ sec}$ .
3. Cooling Speed:  $2 \sim 10^\circ\text{C}/\text{sec}$ .

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度： $260 \pm 5^\circ\text{C}$

时间： $10 \pm 1 \text{ sec}$ 。

Temp.: $260 \pm 5^\circ\text{C}$

Time: $10 \pm 1 \text{ sec}$

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
ABS/LBF	5000	2	10000	5	50000	13" × 15	336X336X40	345X345X235

**使用说明 / Notices**